



Title:

The Art and Science of Packaging High-Coupling Photonics Devices and Modules

Prof. Wood-Hi Cheng

National Sun Yat-sen University

2014/12/24 (Wed.) AM 10:30-11:30



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About the speaker:

Brief biography:

He is a Professor at the Institute of Electro-Optical Engineering and Dean of Engineering, National Sun Yat-sen University, Kaoshiung, Taiwan, R.O.C. His research and development activities have been focused on the design and fabrication of high-speed semiconductor lasers for light-wave communications, highly efficient light coupling from lasers into fibers, fiber couplers, characterization of III-V semiconductor materials, and optoelectronic packaging. His current research interests are the design, fabrication, and finite-element-method analysis for laser module packaging, high-speed laser module packaging for digital lightwave systems, fabrication of high density WDM components, and novel materials for electromagnetic shielding. He served as a consultant for Chunghwa Telecom Laboratories, Opto-Electronics and System Laboratories, and Chung-Shan Institute of Science and Technology, all from Taiwan.

Dr. Cheng is a senior member of IEEE, a member of the Optical Society of America (OSA), and the Photonics Society of Chinese-Americans. He served as a Chair for the IEEE Lasers and Electro-Optics Society (LEOS), Taipei Chapter during 1999 -2000, and serves as a Chair for the OSA, Taipei Chapter.

Present research:

1. Design, fabrication, and finite-element analysis for laser module Packaging.
2. High-speed laser module Packaging.
3. Novel materials for DWDM components and electromagnetic shielding.

Sponsored by:

Department of Photonics, NCKU

